

LAYER STACK UP		CU
LAYER 1 - TOP SIDE (COMPONENT)		1 oz FINISHED MIN.
LAYER 2 - BOTTOM SIDE (SOLDER)		1 oz FINISHED MIN.

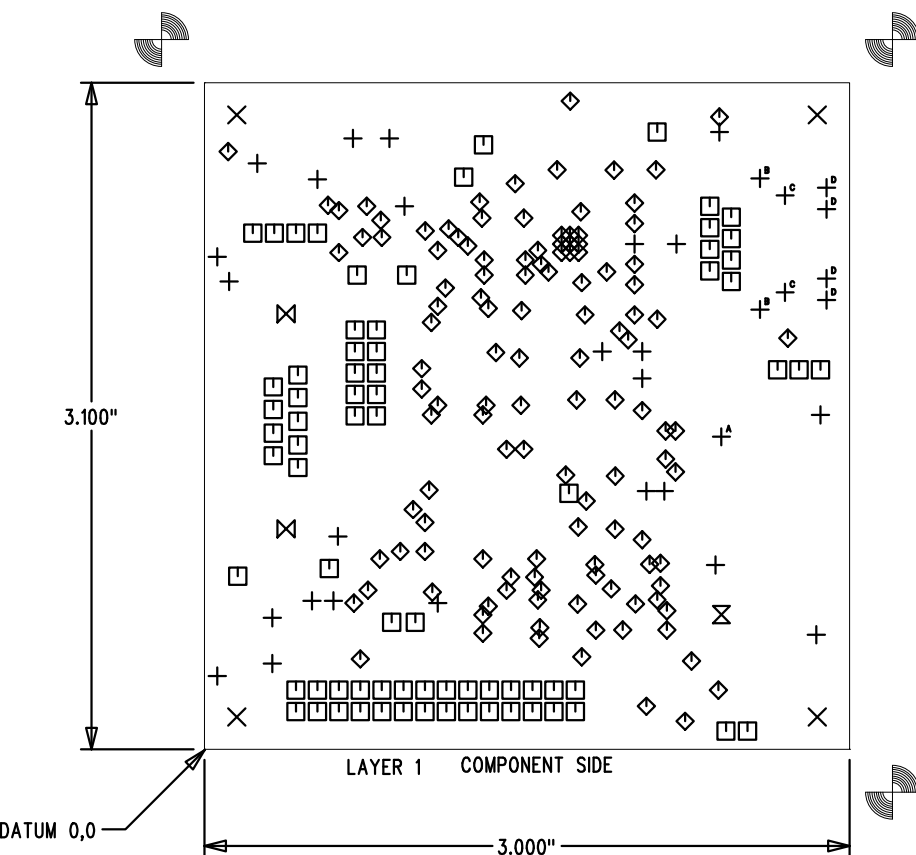
SIZE	QTY	SYM	PLATED	TOL
16	122	◇	YES	+/-
20	25	+	YES	+/-
36	74	□	YES	+/-
40	4	⊕ <sup>D</sup>	YES	+/-
43	1	⊗	YES	+/-
63	1	⊕ <sup>A</sup>	YES	+/-
64	2	⊕ <sup>B</sup>	YES	+/-
120	2	⊗	YES	+/-
128	2	⊕ <sup>C</sup>	YES	+/-
150	4	⊗	YES	+/-

#### FAB NOTES:

- HOLE CHART IS IN MILS.
- BOARD MATERIAL SHALL BE TG-170 °C OR EQUIVALENT. ROHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. COLOR: NATURAL
- BOARD MATERIAL & CONSTRUCTION TO BE U.L. APPROVED AND MARKED ON THE FINISHED BOARD.
- MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .002 INCH.
- OVERALL BOARD THICKNESS TO BE .062 +/- 10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
- MAX WARP & TWIST TO BE .0075 INCHES PER INCH.
- BOARD MUST BE ELECTRICALLY TESTED.

#### PROCESS NOTES:

- SURFACE FINISH SHALL BE IMMERSION GOLD.
- APPLY LPI SOLDERMASK OVER BARE COPPER ( SMOBC ) COLOR: GREEN.
- FABRICATION VENDOR IS ALLOWED TO ADJUST THE COMPONENT SOLDERMASK PADS TO MEET THEIR TOOLING REQUIREMENTS.
- SILKSCREEN TOP SIDE USING NON-CONDUCTIVE EPOXY INK. COLOR: WHITE.



### TIN CAN TOOLS, LLC.

BOARD NAME		
Zippy II Ethernet Combo Board		
DESCRIPTION	DRILL DRAWING	REV B
DATE	NOVEMBER 2, 2009	SH 1 OF 1